

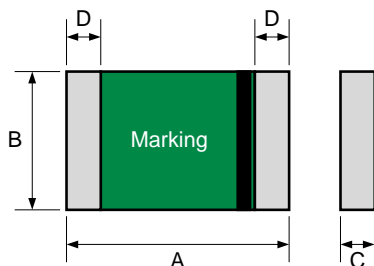
## Features

- Small size of 1812
- Fast tripping resettable circuit protection
- Surface mount packaging for automated assembly
- Agency Recognition: UL, CSA, TUV

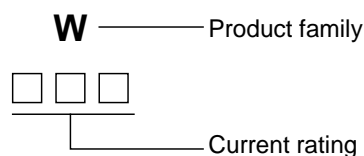


## Product Dimensions (mm)

Part number	A	B	C	D
	Max.	Max.	Max.	Max.
LP-MSM014	4.73	3.41	0.81	0.60



## Part Marking System



## Electrical Characteristics

Part number	$I_H$ (A)	$I_T$ (A)	$V_{max}$ (V)	$I_{max}$ (A)	$T_{trip}$ Current(A) Time(S)	$P_{dtyp}$ (W)	$R_{min}$ ( $\Omega$ )	$R_{1max}$ ( $\Omega$ )
LP-MSM014	0.14	0.34	60	10	1.5 0.15	1.0	0.70	6.00

$I_H$ =Hold current: maximum current at which the device will not trip at 25 °C still air.

$I_T$ =Trip current: minimum current at which the device will always trip at 25 °C still air.

$V_{max}$ =Maximum voltage device can withstand without damage at rated current.

$I_{max}$ =Maximum fault current device can withstand without damage at rated voltage.

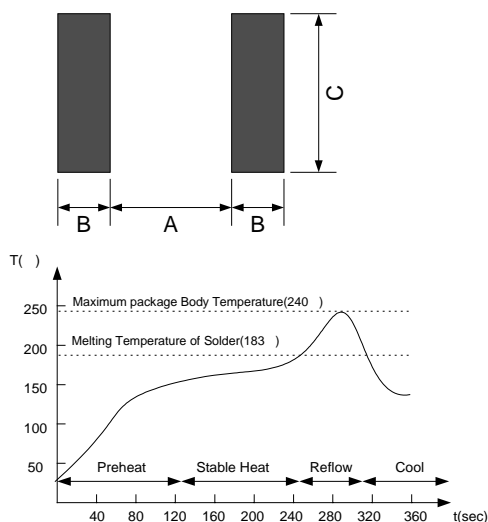
$T_{trip}$ =Maximum time to trip(s) at assigned current.

$P_{dtyp}$ =Typical power dissipation: typical amount of power dissipated by the device when in state air environment.

$R_{min}$ =Minimum device resistance at 25 °C prior to tripping.

$R_{1max}$ =Maximum device resistance measured in the nontripped state 1 hour post reflow.

## Solder Reflow Recommendations



## Solder Pad Layouts

Part number	A (mm)	B (mm)	C (mm)
LP-MSM014	3.45	1.78	3.15

\* Recommended reflow methods: IR, Vapor phase oven, hot air oven, wave solder.

\* Devices can be cleaned using standard industry methods and solvents.

### Notes:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

## Package Information

Tape & Reel: 2000pcs per reel.